

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<u>In re</u> application of:)	
)	Group Art Unit: 3744
Chen et al.)	
)	Examiner: CIRIC, L.
Application No.: 10/712,708)	
)	Docket No.: JLINP174/TLC
Filed: November 12, 2003)	
)	Date: February 23, 2009
For: <u>HEAT DISSIPATION MODULE</u>)	

CERTIFICATE OF E-Filing

I hereby certify that this paper and the documents and/or fees referred to as attached herein are being electronically filed with the United States Postal Service on **February 23, 2009**.
/Kay Harlow/

RESPONSE AND AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This paper is in response to the Office communication mailed on January 23, 2009. Applicants respectfully submit comments in connection with the above-named application.

Amendments to the claims are reflected in the listing of claims which begin on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.